

uPOL MODULE

1A, High Efficiency uPOL Module

MUN3CAD01-SC

FEATURES:

- High Density Integration Module
- IA Output Current
- 93% Peak Efficiency at 3.3VIN
- Input Voltage Range from 2.7V to 5.5V
- Output Voltage Range from 0.8V to 4.0V
- Enable Function
- Automatic Power Saving/PWM Mode
- Protections (UVLO, OCP: Non-latching)
- Internal Soft Start
- Compact Size: 2.9mm*2.3mm*1.05mm
- Pb-free for RoHS compliant
- MSL 2, 260°C Reflow

APPLICATIONS:

- Single Li-Ion Battery-Powered Equipment
- LDOs Replacement
- Cell Phones / PDAs / Palmtops

GENERAL DESCRIPTION:

The uPOL module is non-isolated dc-dc converter that can deliver up to 1A of output current. The PWM switching regulator, high frequency power inductor, input/output bulk capacitors are integrated in one hybrid package.

The module has automatic operation with PWM mode and power saving mode according to loading. Other features include remote enable function, internal soft-start, non-latching over current protection, short circuit protection and input under voltage locked-out capability.

The low profile and compact size package $(2.9 \text{ mm} \times 2.3 \text{ mm} \times 1.05 \text{ mm})$ is suitable for automated assembly by standard surface mount equipment. The module is Pb-free and RoHS compliance.

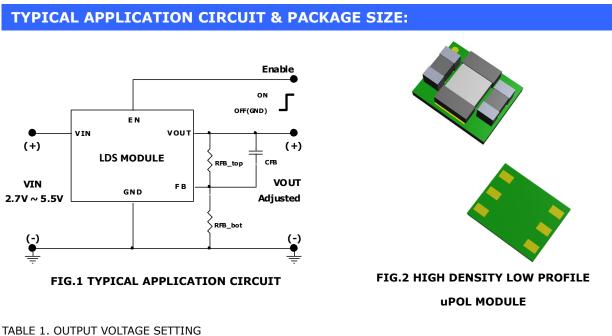


TABLE 1. OUTPUT VOLIAGE SETTING

Vout	1.0V	1.2V	1.5V	1.8V	2.5V	3.3V
$RFB_top(\Omega)$		100k				
$RFB_bot(\Omega)$	150k	100k	66.5k	50k	31.6k	22.1k

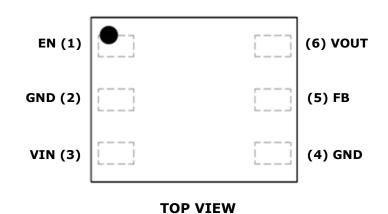


ORDER INFORMATION:

Part Number	Ambient Temp. Range (°C)	Package (Pb-Free)	MSL	Note
MUN3CAD01-SC	-40 ~ +85	DFN	Level 2	-

Order Code	Packing	Quantity
MUN3CAD01-SC	Tape and reel	2000

PIN CONFIGURATION:



PIN DESCRIPTION:

Symbol	Pin No.	Description	
EN	1	On/Off control pin for module. EN = LOW, the module is off. EN = HIGH, the module is on. Do not float.	
GND	2, 4	Power ground pin for signal, input, and output return path. This pin needs to connect one or more ground plane directly.	
VIN	3	Power input pin. It needs to connect input rail.	
FB	5	Feedback input. Connect to output through a voltage dividing resistors for adjusting output voltage. Place those resistors as closely as possible to this pin.	
VOUT	6	Power output pin. Connect to output for the load.	



ELECTRICAL SPECIFICATIONS:

CAUTION: Do not operate at or near absolute maximum rating listed for extended periods of time. This stress may adversely impact product reliability and result in failures not covered by warranty.

Parameter	Description	Min.	Тур.	Max.	Unit		
 Absolute Maxim 	Absolute Maximum Ratings						
VIN to GND	Note 1	-	-	+6.0	V		
VOUT to GND	Note 1	-	-	+6.0	V		
EN to GND	Note 1	-	-	VIN+0.6	V		
Тс	Case Temperature of Inductor	-	-	+110	°C		
Tj	Junction Temperature	-40	-	+150	°C		
Tstg	Storage Temperature	-40	-	+125	°C		
	Human Body Model (HBM)	-	-	2k	V		
ESD Rating	Machine Model (MM)	-	-	200	V		
	Charge Device Model (CDM)	-	-	1k	V		
Recommendation	 Recommendation Operating Ratings 						
VIN	Input Supply Voltage	+2.7	-	+5.5	V		
VOUT	Output Voltage	+0.8	-	+4.0	V		
Та	Ambient Temperature	-40	-	+85	°C		
 Thermal Inform 	Thermal Information						
Rth(jchoke-a)	Thermal resistance from junction to ambient. (Note 1)	-	70	-	°C/W		

NOTES:

 Rth(jchoke-a) is measured with the component mounted on an effective thermal conductivity test board on 0 LFM condition. The test board size is 30mm×30mm×1.6mm with 2 layers, 1oz. The test condition is complied with JEDEC EIJ/JESD 51 Standards.



ELECTRICAL SPECIFICATIONS: (Cont.)

Conditions: $T_A = 25 \text{ °C}$, unless otherwise specified. Test Board Information: $30 \text{ mm} \times 30 \text{ mm} \times 1.6 \text{ mm}$, 4 layers 202 . The output ripple and transient response measurement is short loop probing and 20MHz bandwidth limited.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
 Input 	 Input Characteristics 						
$I_{\text{SD(IN)}}$	Input shutdown current	Vin = 3.3V, EN = GND	-	0.3	1	uA	
$I_{(IN)}$	Input supply current	Vin = 3.3V, Iout = 0A EN = VIN Vout = 1.8V	-	75	-	uA	
		Vin = 3.3V, EN = VIN	-		-	-	
	Input supply	Iout = 5mA Vout = 1.8V	-	3	-	mA	
$I_{S(IN)}$	current	Iout = 100mA Vout = 1.8V	-	66	-	mA	
		Iout = 1000mA Vout = 1.8V	-	730	-	mA	
 Outp 	ut Characteristic	S					
I _{OUT(DC)}	Output continuous current range	Vin=3.3V, Vout=1.8V	0	-	1000	mA	
V _{O(SET)}	Ouput Voltage set Point	With 0.5% tolerance for external resistor used to set output voltage	-3.0		+3.0	% V _{O(SET)}	
ΔV_{OUT} / ΔV_{IN}	Line regulation accuracy	Vin = 3.3V to 5V Vout = 1.8V, Iout = 200mA Vout = 1.8V, Iout = 1000mA	-	0.1	1.0	% V _{O(SET)}	
ΔV_{OUT}	Load regulation accuracy	Iout = 200mA to 1000mA Vin = 3.3V, Vout = 1.8V	-	0.5	1.0	% V _{O(SET)}	
V _{OUT(AC)}	Output ripple voltage	Vin = 3.3V, Vout = 1.8V EN = VIN	-	-	-	-	
		IOUT = 5mA,		20		mVp-p	
		IOUT = 1000mA,		15		mVp-p	
Cout(max)	Maximum capacitive load	Iout = 1000mA, ESR \ge 1 m Ω			150	uF	



ELECTRICAL SPECIFICATIONS: (Cont.)

Conditions: $T_A = 25 \text{ °C}$, unless otherwise specified. Test Board Information: $30 \text{ mm} \times 30 \text{ mm} \times 1.6 \text{ mm}$, 4 layers 20z. The output ripple and transient response measurement is short loop probing and 20 MHz bandwidth limited.

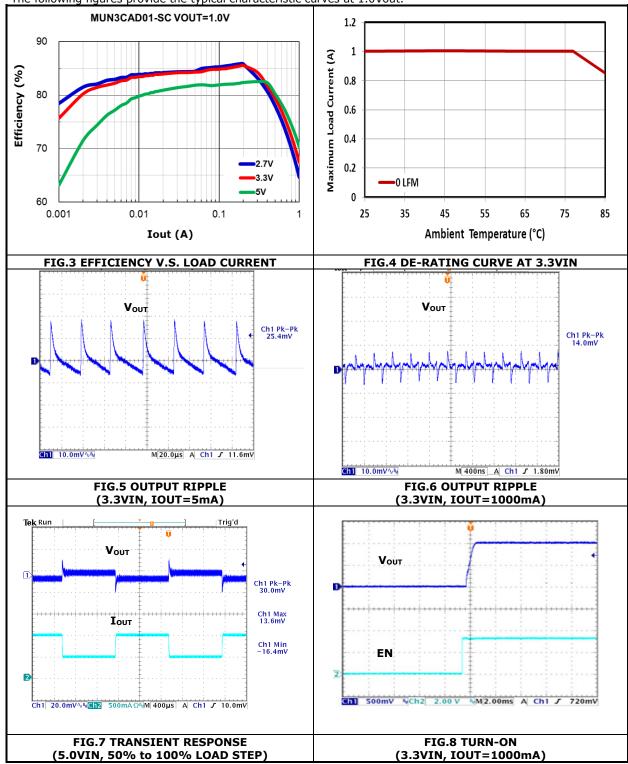
Vin = 3.3V, Vout = 1.8V, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
Cont	Control Characteristics						
Vref	Referance voltage		0.588	0.6	0.612	V	
Fosc	Oscillator frequency	PWM Operation	-	3.0	-	MHz	
V	Enable rising threshold voltage		1.5	-	-	V	
$V_{EN_{TH}}$	Enable falling threshold voltage		-	-	0.4	V	
Fault	Fault Protection						
Vuvlo_th	Input under voltage lockout threshold	Falling,	-	2.5	-	V	
Тотр	Over temp protection		-	160	-	°C	
I _{LIMIT_TH}	Current limit threshold	Peak value of inductor current,	1.3	-	2.5	А	



TYPICAL PERFORMANCE CHARACTERISTICS: (1.0VOUT)

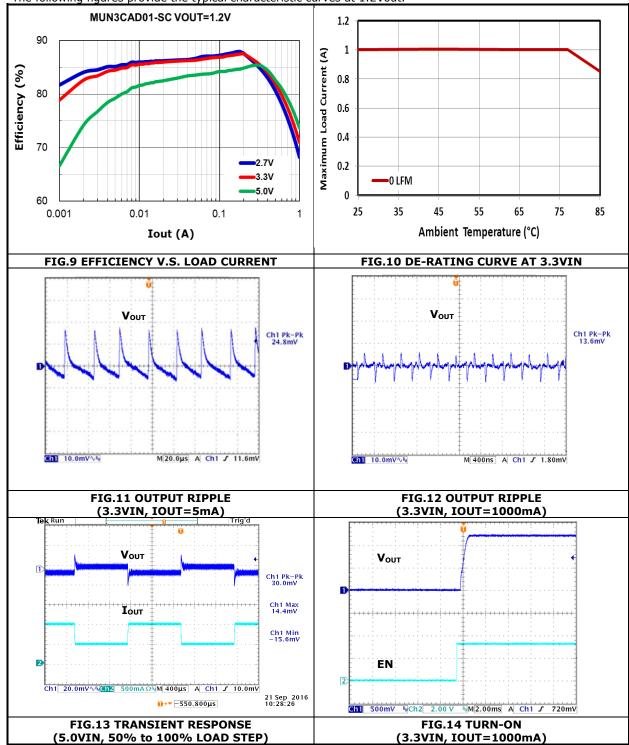
Conditions: $T_A = 25 \text{ °C}$, unless otherwise specified. Test Board Information: $30 \text{ mm} \times 30 \text{ mm} \times 1.6 \text{ mm}$, 4 layers 20z. The output ripple and transient response measurement is short loop probing and 20 MHz bandwidth limited. The following figures provide the typical characteristic curves at 1.0Vout.





TYPICAL PERFORMANCE CHARACTERISTICS: (1.2VOUT)

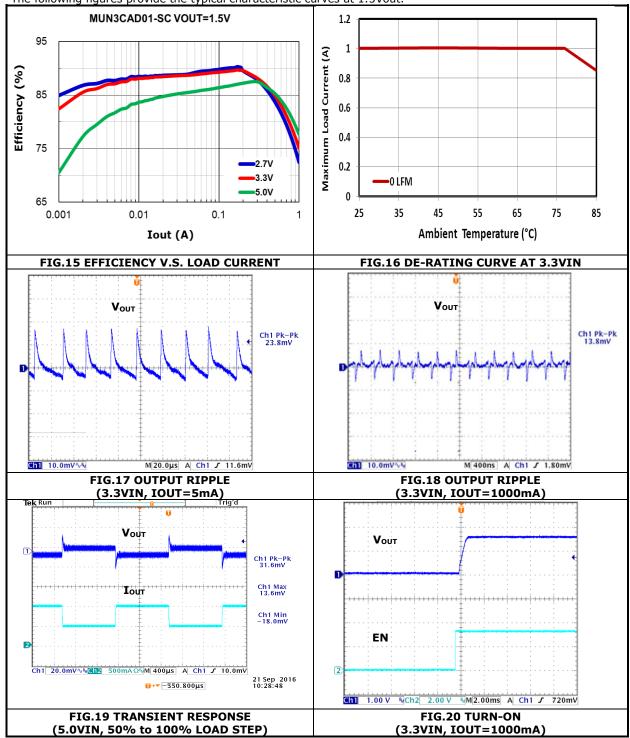
Conditions: $T_A = 25 \text{ °C}$, unless otherwise specified. Test Board Information: $30 \text{ mm} \times 30 \text{ mm} \times 1.6 \text{ mm}$, 4 layers 202 .The output ripple and transient response measurement is short loop probing and 20 MHz bandwidth limited. The following figures provide the typical characteristic curves at 1.2 Vout.





TYPICAL PERFORMANCE CHARACTERISTICS: (1.5VOUT)

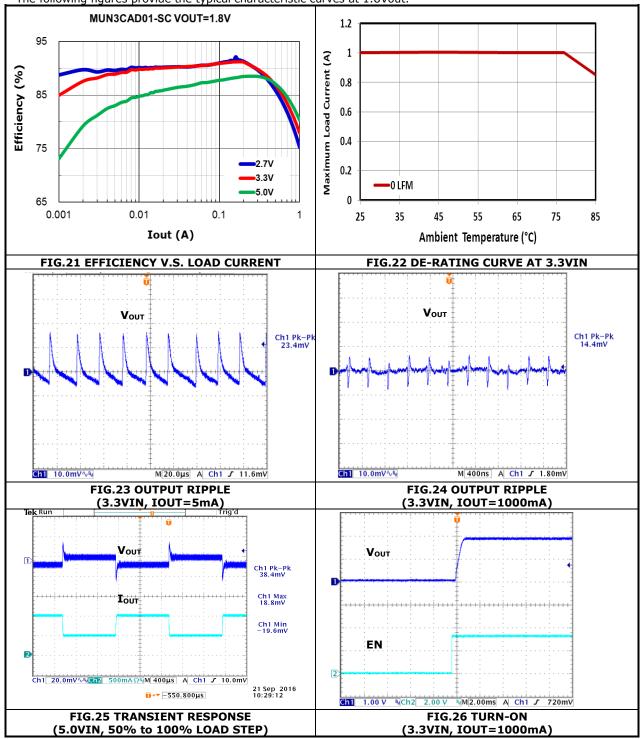
Conditions: $T_A = 25 \text{ }^{\circ}\text{C}$, unless otherwise specified. Test Board Information: $30 \text{mm} \times 30 \text{mm} \times 1.6 \text{mm}$, 4 layers 202. The output ripple and transient response measurement is short loop probing and 20 MHz bandwidth limited. The following figures provide the typical characteristic curves at 1.5 Vout.





TYPICAL PERFORMANCE CHARACTERISTICS: (1.8VOUT)

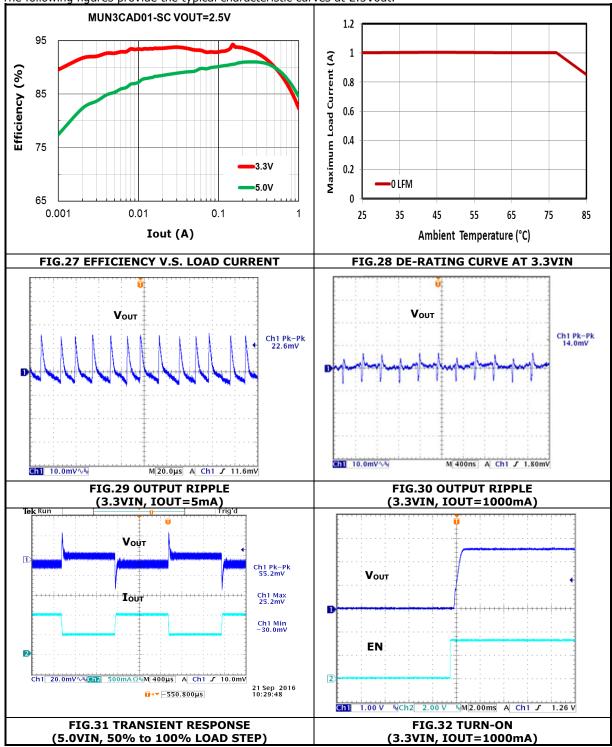
Conditions: $T_A = 25 \text{ °C}$, unless otherwise specified. Test Board Information: $30 \text{ mm} \times 30 \text{ mm} \times 1.6 \text{ mm}$, 4 layers 202 .The output ripple and transient response measurement is short loop probing and 20 MHz bandwidth limited. The following figures provide the typical characteristic curves at 1.8Vout.





TYPICAL PERFORMANCE CHARACTERISTICS: (2.5VOUT)

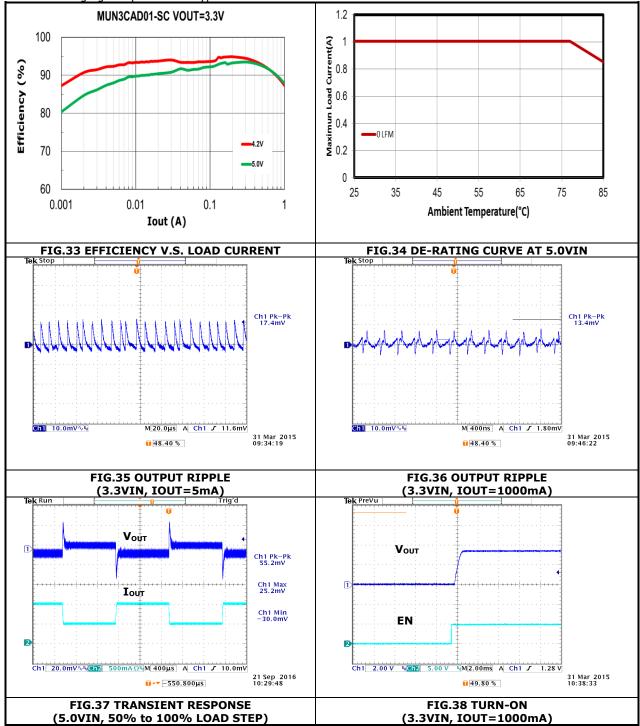
Conditions: $T_A = 25 \text{ °C}$, unless otherwise specified. Test Board Information: $30 \text{ mm} \times 30 \text{ mm} \times 1.6 \text{ mm}$, 4 layers 202 .The output ripple and transient response measurement is short loop probing and 20 MHz bandwidth limited. The following figures provide the typical characteristic curves at 2.5Vout.





TYPICAL PERFORMANCE CHARACTERISTICS: (3.3VOUT)

Conditions: $T_A = 25 \text{ °C}$, unless otherwise specified. Test Board Information: $30 \text{ mm} \times 30 \text{ mm} \times 1.6 \text{ mm}$, 4 layers 202 .The output ripple and transient response measurement is short loop probing and 20 MHz bandwidth limited. The following figures provide the typical characteristic curves at 3.3 Vout.





APPLICATIONS INFORMATION:

REFERENCE CIRCUIT FOR GENERAL APPLICATION:

The Figure 39 shows the module application schematics for input voltage +5V or +3.3V and turn on by input voltage directly through enable resistor (REN).

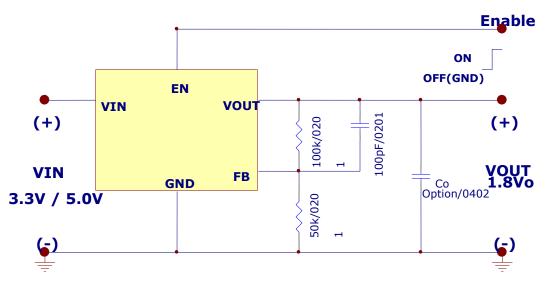


FIG.39 TYPICAL APPLICATION FOR PWM OPERATION



APPLICATIONS INFORMATION: (Cont.)

SAFETY CONSIDERATIONS:

Certain applications and/or safety agencies may require fuses at the inputs of power conversion components. Fuses should also be used when there is the possibility of sustained input voltage reversal which is not current limited. For greatest safety, we recommend a fast blow fuse installed in the ungrounded input supply line. The installer must observe all relevant safety standards and regulations. For safety agency approvals, install the converter in compliance with the end-user safety standard.

OUTPUT FILTERING:

To reduce output ripple and improve the dynamic response as the step load changes, an additional capacitor at the output must be connected. Low ESR polymer and ceramic capacitors are recommended to improve the output ripple and dynamic response of the module.

PROGRAMMING OUTPUT VOLTAGE:

The module has an internal 0.6V±2% reference voltage. The output voltage can be programed by the dividing resistor RFB which respects to FB pin and GND pin. The output voltage can be calculated as shown in Equation 1 and the resistor according to typical output voltage is shown in TABLE 1.

$$VOUT (V) = 0.6 \times \left(1 + \frac{100k}{RFB}\right)$$
(EQ.1)



APPLICATIONS INFORMATION: (Cont.)

RECOMMENDATION LAYOUT GUIDE:

In order to achieve stable, low losses, less noise or spike, and good thermal performance some layout considerations are necessary. The recommendation layout is shown as Figure 40.

- 1. The ground connection between pin 2 and 4 should be a solid ground plane under the module. It can be connected one or more ground plane by using several Vias.
- 2. Place high frequency ceramic capacitors between pin 3 (VOUT), and pin 2, 4 (GND) for output side, as close to module as possible to minimize high frequency noise.
- 3. Keep the $R_{FB_{top}}$, $R_{FB_{bot}}$, and CFF connection trace to the module pin 5 (FB) short.
- 4. Use large copper area for power path (VIN, VOUT, and GND) to minimize the conduction loss and enhance heat transferring. Also, use multiple Vias to connect power planes in different layer.

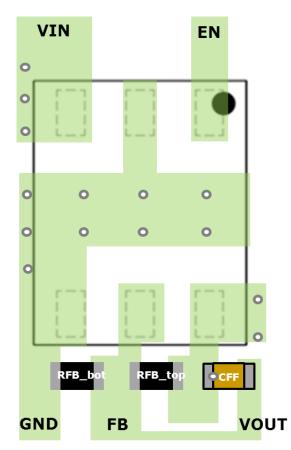


FIG.40 RECOMMENDATION LAYOUT (TOP LAYER)



APPLICATIONS INFORMATION: (Cont.)

Thermal Considerations:

All of thermal testing condition is complied with JEDEC EIJ/JESD 51 Standards. Therefore, the test board size is 30mm×30mm×1.6mm with 2 layers. The case temperature of module sensing point is shown as Figure 41. Then Rth(j_{choke}-a) is measured with the component mounted on an effective thermal conductivity test board on 0 LFM condition. The MUN3CAD01-SC module is designed for using when the case temperature is below 110°C regardless the change of output current, input/output voltage or ambient temperature.

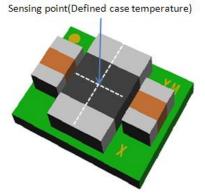
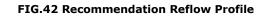


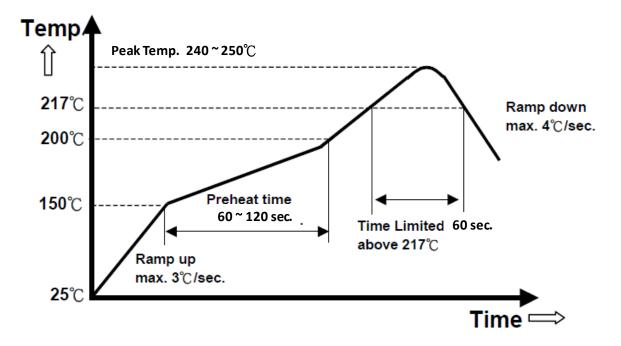
FIG.41 Case Temperature Sensing Point



REFLOW PARAMETERS:

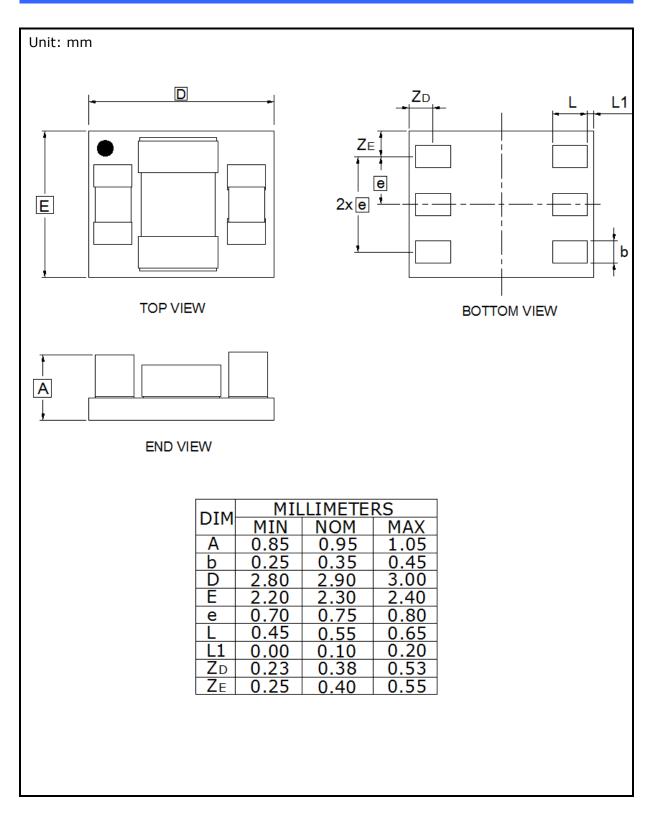
Lead-free soldering process is a standard of electronic products production. Solder alloys like Sn/Ag, Sn/Ag/Cu and Sn/Ag/Bi are used extensively to replace the traditional Sn/Pb alloy. Sn/Ag/Cu alloy (SAC) is recommended for this power module process. In the SAC alloy series, SAC305 is a very popular solder alloy containing 3% Ag and 0.5% Cu and easy to obtain. Figure 36 shows an example of the reflow profile diagram. Typically, the profile has three stages. During the initial stage from room temperature to 150°C, the ramp rate of temperature should not be more than 3°C/sec. The soak zone then occurs from 150°C to 200°C and should last for 60 to 120 seconds. Finally, keep at over 217°C for 60 seconds limit to melt the solder and make the peak temperature at the range from 240°C to 250°C. It is noted that the time of peak temperature should depend on the mass of the PCB board. The reflow profile is usually supported by the solder vendor and one should adopt it for optimization according to various solder type and various manufacturers' formulae.





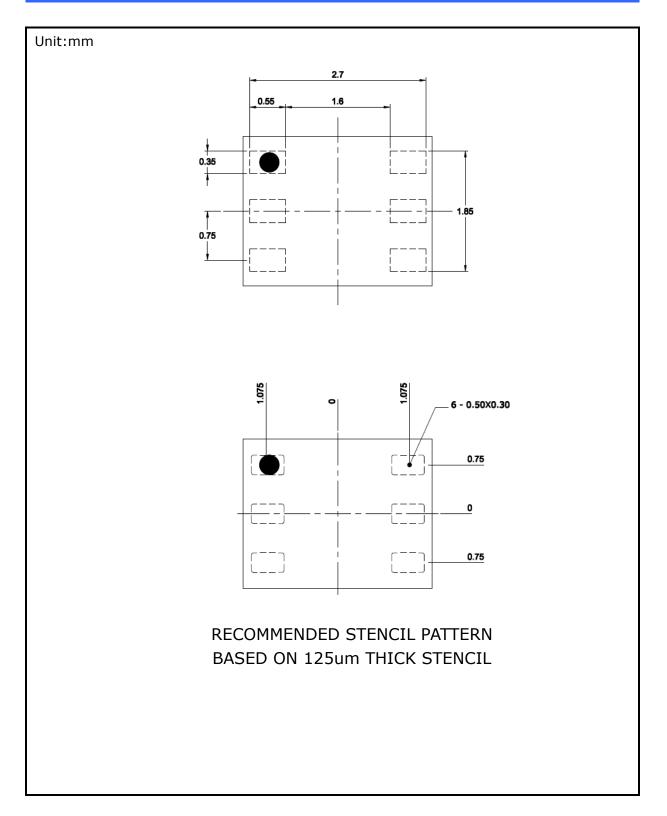


PACKAGE OUTLINE DRAWING:



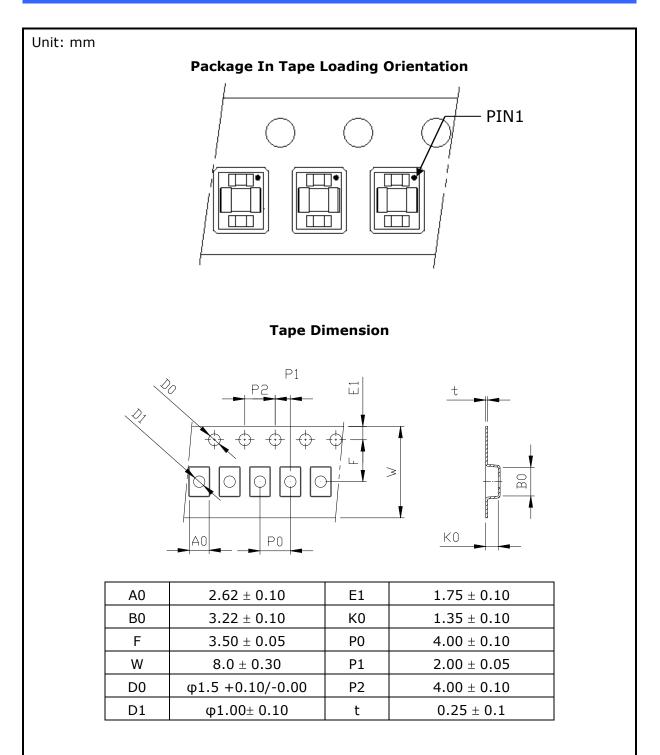


LAND PATTERN REFERENCE:

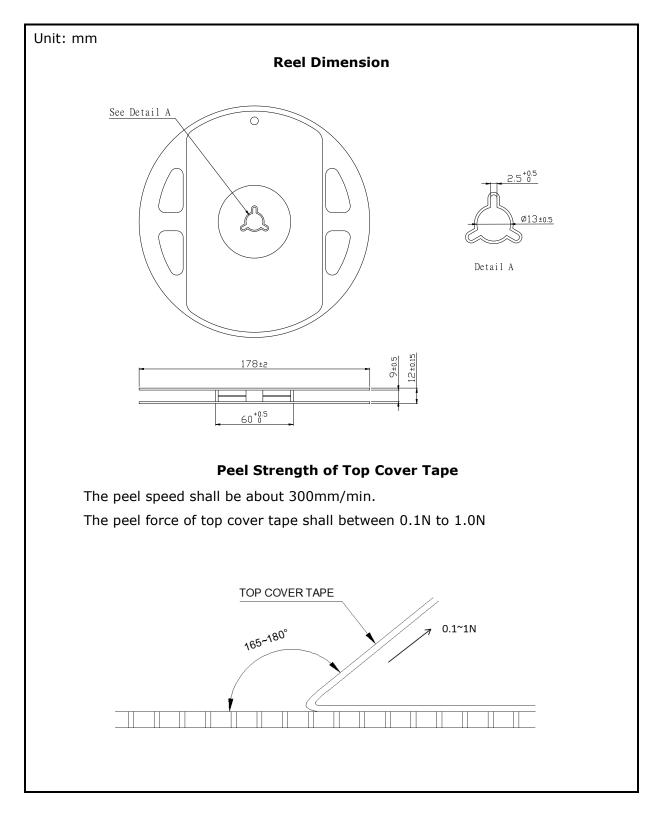




PACKING REFERENCE:









REVERSION HISTORY:

Date	Revision	Changes	
2015.01.08	00	Initial released.	
2015.03.31	01	Official released.	
2015.06.24	02	Add REFLOW PARAMETERS	
2015.09.17	03	Upgrade Input shutdown current	
2016.03.29	04	Upgrade Compact Size 1.0mm→1.05mm	
2016.09.19	05	Add ORDER INFORMATION	
2010.09.19	05	Upgrade Current limit threshold	
2016.12.27	05	Page 1 Revision Rev 04. Change to Rev 05.	
2017.3.29	06	Add VOUT=3.3V Performance Characteristics	
2018.12.27	07	Upgrade line regulation and load regulation	

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 URA2412YMD-15WR3
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 VRB2405LD-15WR3
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 RD5-110S05W
 RD5

 110S12W
 RD25-5S12F
 MAS15-12-W
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 TAS5-15-WEDT
 WRB1209S-3WR2
 ZY2424FLS-1W
 ZY0505AS-1W
 ZY2412IFS-1W

 ZY0512FS-1W
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